

	Hits	Search Text	DBs
14	50	((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and ((transfer\$3 or roll\$3 or collector) same (blanket or layer or film)) and (print\$3 near5 roll\$3) and ((substrate or transfer) same (metal\$4 or semiconductor or "SiO.sub.2" or SiO\$2 or insulat\$4) same (photoresist or resist)) and ((substrate or clich\$3) same (etch\$4 near5 (object or process\$4)) same (fill\$4 or deposit\$4 or form\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
15	45	((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and ((transfer\$3 or roll\$3 or collector) same (blanket or layer or film) same (print\$3 near9 roll\$3)) and ((substrate or transfer) same (metal\$4 or semiconductor or "SiO.sub.2" or SiO\$2 or insulat\$4) same (photoresist or resist)) and ((substrate or clich\$3) same (etch\$4 near5 (object or process\$4)) same (fill\$4 or deposit\$4 or form\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
16	14	((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and ((transfer\$3 or roll\$3 or collector) same (blanket or film or layer) same (print\$3 near9 roll\$3)) and ((substrate or transfer) same (metal\$4 or semiconduct\$4 or "SiO.sub.2" or SiO\$2 or insulat\$4 or dielectric or silica or conductive) same (photoresist or resist)) and ((substrate or clich\$3) same (etch\$4 near5 (object or process\$4)) same (fill\$4 or deposit\$4 or form\$3)) and (gravur\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
17	5	((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and ((transfer\$3 or roll\$3 or collector) same (blanket or film or layer) same (print\$3 near9 roll\$3) same (resist or photoresist or (cur\$4 near12 material)) same gravur\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
18	12	((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and ((transfer\$3 or roll\$3 or collector) same (blanket or film or layer) same (print\$3 near9 roll\$3) same (resist or photoresist or (cur\$4 near12 material))) and (gravur\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB